

An evaluation of the thin film measured using high-brilliance and high-intensity X-ray reflectivity instrument

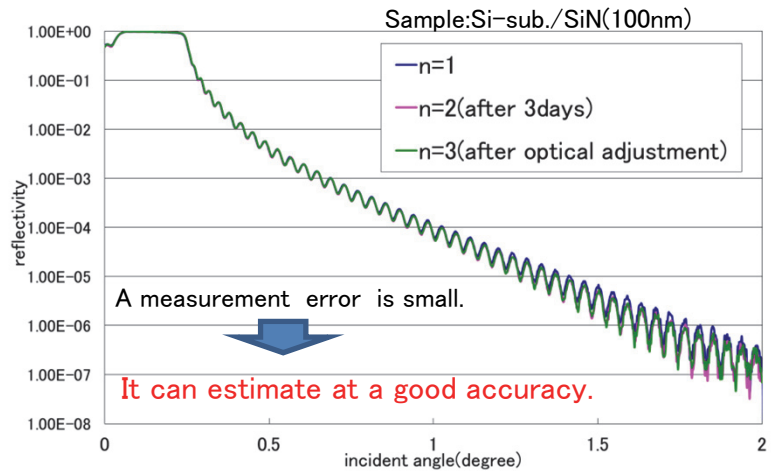
The new X-ray reflectivity instrument we introduced can evaluate a thickness and density of a ultra thin film and characterize a interface. Furthermore, we can know the whole pattern of the thin film on the wafer by a mapping mode measurement.

The new X-ray reflectivity instrument

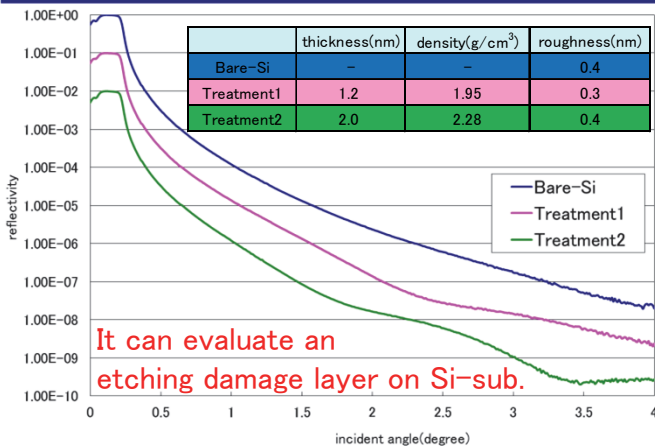
- The high-brilliance and high-intensity X-ray source.
- The dynamic range improved widely.



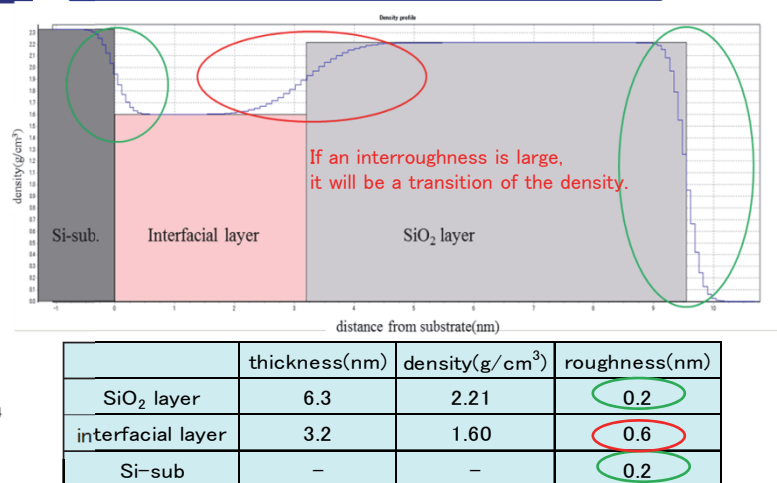
A good precision at the measurement



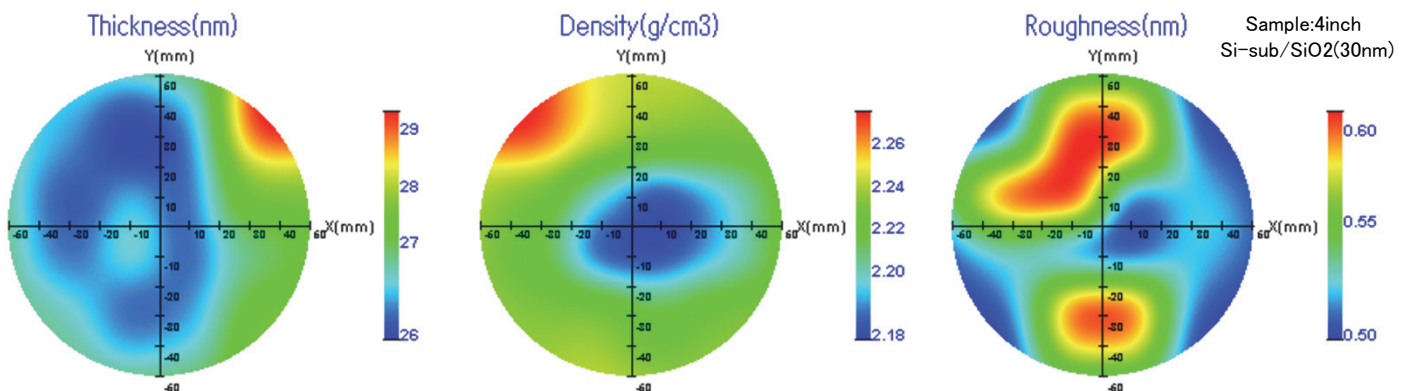
An evaluate a thickness and density of a ultra thin film



A depth profile of the density



A mapping mode measurement



It can measure non-destructively until a 12inch wafer.